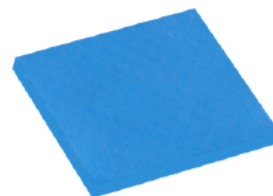


## High Performance Gap Filler Pad

TP700-7-50 thermal conductive silicone pad is a kind of material with high thermal conductivity. It is double-sided self-adhesive. When assembling with electronic components, it shows low thermal resistance and better electrical insulation characteristics under low compression force. It can work stably at  $-40^{\circ}\text{C} \sim 150^{\circ}\text{C}$  and meet the flame retardant grade requirements of UL94V0.



### Features and Benefits

- 7.0 W/m.K
- Naturally tacky, easing application
- Excellent, high volume applications
- High thermal conductivity

### Typical Applications

- Networking and Telecommunications
- IT: BGA, ASIC, VRM, high speed storage
- Industrial: LEDs, Power Supplies and Conversion
- Automotive: Control Modules, Turbo Actuators
- Consumer Electronics: Gaming Systems, LCDs, and Graphic Cards

### HOW TO ORDER

Patron THER TP700-7-50 XXX-YYY-ZZmm  
XXX = width in mm  
YYY = depth in mm  
ZZ = thickness in mm

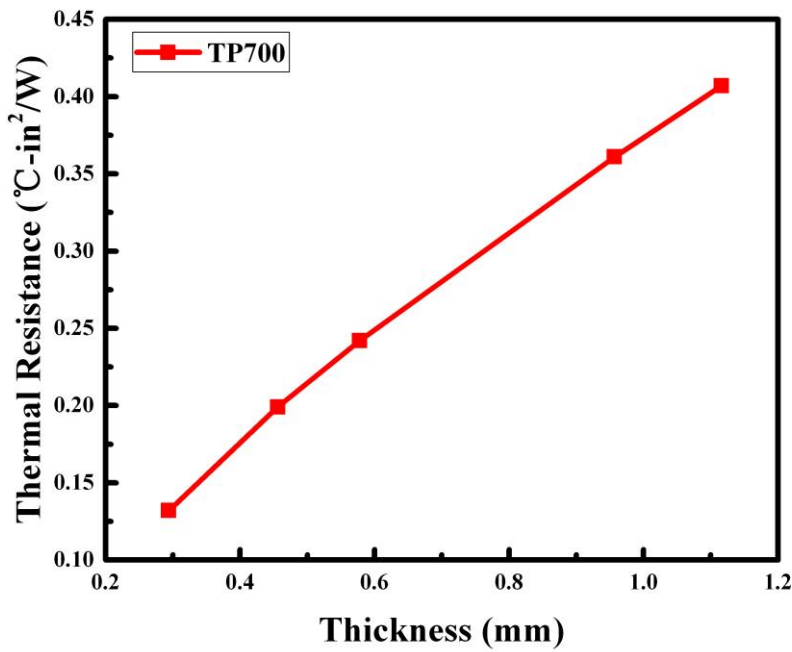
### TYPICAL PROPERTIES

Attribute	Value	Test Method
	<b>TP700-7-50</b>	-
Composition	Ceramic Filler + Silicone	-
Color	Light Blue	Visual
Thickness (mm)	0.5 to 10.0	ASTM D374
Density (g/cc)	3.3	ASTM D792
Hardness (Shore OO)	50(Thickness $\leq$ 1.0 Shore OO 55)	ASTM D2240
Usage Temperature ( $^{\circ}\text{C}$ )	- 40 to 150	-
<b>Electrical</b>		
Breakdown Voltage (kV/mm)	$>6.0$	ASTM D149
Volume Resistivity ( $\Omega\cdot\text{cm}$ )	$10^{12}$	ASTM D257
Dielectric Constant @1MHz	7.1	ASTM D150
Flammability	V-0	UL 94
<b>Thermal</b>		
Thermal Conductivity (W/m.K)	7.0	ISO 22007-2

## High Performance Gap Filler Pad

### Thickness vs. Thermal Resistance

Reference only



### Pressure vs. Deflection

Reference only

